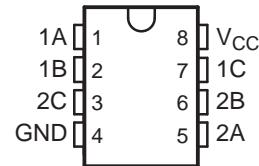


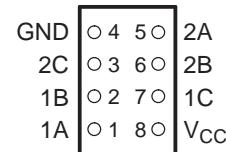
## FEATURES

- Available in the Texas Instruments NanoFree™ Package
- Operates at 0.8 V to 2.7 V
- Sub-1-V Operable
- Max  $t_{pd}$  of 0.5 ns at 1.8 V
- Low Power Consumption, 10  $\mu$ A at 2.7 V
- High On-Off Output Voltage Ratio
- High Degree of Linearity
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Performance Tested Per JESD 22
  - 2000-V Human-Body Model (A114-B, Class II)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)

DCT OR DCU PACKAGE  
(TOP VIEW)



YZP PACKAGE  
(BOTTOM VIEW)



## DESCRIPTION/ORDERING INFORMATION

This dual analog switch is operational at 0.8-V to 2.7-V  $V_{CC}$ , but is designed specifically for 1.1-V to 2.7-V  $V_{CC}$  operation.

The SN74AUC2G66 can handle both analog and digital signals. It permits signals with amplitudes of up to 2.7-V (peak) to be transmitted in either direction.

NanoFree™ package technology is a major breakthrough in IC packaging concepts, using the die as the package.

Applications include signal gating, chopping, modulation or demodulation (modem), and signal multiplexing for analog-to-digital and digital-to-analog conversion systems.

## ORDERING INFORMATION

$T_A$	PACKAGE <sup>(1)</sup>	ORDERABLE PART NUMBER	TOP-SIDE MARKING <sup>(2)</sup>
-40°C to 85°C	NanoFree™ – W CSP (DSBGA) 0.23-mm Large Bump – YZP (Pb-free)	Reel of 3000	SN74AUC2G66YZPR _ _ _ U6 _
	SSOP – DCT	Reel of 3000	SN74AUC2G66DCTR U66_ _ _
	VSSOP – DCU	Reel of 3000	SN74AUC2G66DCUR U66_

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).

(2) DCT: The actual top-side marking has three additional characters that designate the year, month, and assembly/test site.

DCU: The actual top-side marking has one additional character that designates the assembly/test site.

YZP: The actual top-side marking has three preceding characters to denote year, month, and sequence code, and one following character to designate the assembly/test site. Pin 1 identifier indicates solder-bump composition (1 = SnPb, • = Pb-free).

## FUNCTION TABLE

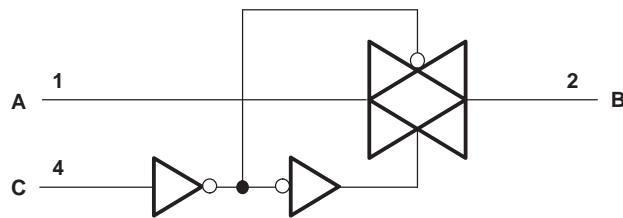
CONTROL INPUT (C)	SWITCH
L	OFF
H	ON



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

NanoFree is a trademark of Texas Instruments.

**LOGIC DIAGRAM (POSITIVE LOGIC)**



**Absolute Maximum Ratings<sup>(1)</sup>**

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
$V_{CC}$	Supply voltage range <sup>(2)</sup>	-0.5	3.6	V
$V_I$	Input voltage range <sup>(2)(3)</sup>	-0.5	3.6	V
$V_{I/O}$	Switch I/O voltage range <sup>(2)(3)</sup>	-0.5	$V_{CC} + 0.5$	V
$I_{IK}$	Control input clamp current	$V_I < 0$	-50	mA
$I_{IOK}$	I/O port diode current	$V_{I/O} < 0$ or $V_{I/O} > V_{CC}$	$\pm 50$	mA
$I_T$	On-state switch current	$V_{I/O} = 0$ to $V_{CC}$	$\pm 50$	mA
	Continuous current through $V_{CC}$ or GND		$\pm 100$	mA
$\theta_{JA}$	Package thermal impedance <sup>(4)</sup>	DCT package	220	°C/W
		DCU package	227	
		YZP package	102	
$T_{stg}$	Storage temperature range	-65	150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltages are with respect to ground unless otherwise specified.
- (3) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
- (4) The package thermal impedance is calculated in accordance with JESD 51-7.

**Recommended Operating Conditions<sup>(1)</sup>**

			MIN	MAX	UNIT
V <sub>CC</sub> Supply voltage			0.8	2.7	V
V <sub>IH</sub> High-level input voltage	V <sub>CC</sub> = 0.8 V		V <sub>CC</sub>		V
	V <sub>CC</sub> = 1.1 V to 1.95 V		0.65 × V <sub>CC</sub>		
	V <sub>CC</sub> = 2.3 V to 2.7 V		1.7		
V <sub>IL</sub> Low-level input voltage	V <sub>CC</sub> = 0.8 V		0		V
	V <sub>CC</sub> = 1.1 V to 1.95 V		0.35 × V <sub>CC</sub>		
	V <sub>CC</sub> = 2.3 V to 2.7 V		0.7		
V <sub>I/O</sub> I/O port voltage			0	V <sub>CC</sub>	V
V <sub>I</sub> Control input voltage			0	3.6	V
Δt/Δv Input transition rise or fall rate	V <sub>CC</sub> = 0.8 V to 1.65 V <sup>(2)</sup>		20		ns/V
	V <sub>CC</sub> = 1.65 V to 2.3 V <sup>(3)</sup>		20		
	V <sub>CC</sub> = 2.3 V to 2.7 V <sup>(3)</sup>		20		
T <sub>A</sub> Operating free-air temperature			-40	85	°C

(1) All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

(2) The data was taken at C<sub>L</sub> = 15 pF, R<sub>L</sub> = 2 kΩ (see [Figure 1](#)).

(3) The data was taken at C<sub>L</sub> = 30 pF, R<sub>L</sub> = 500 Ω (see [Figure 1](#)).

**Electrical Characteristics**

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	MIN	TYP <sup>(1)</sup>	MAX	UNIT
r <sub>on</sub> On-state switch resistance	V <sub>I</sub> = V <sub>CC</sub> or GND, V <sub>C</sub> = V <sub>IH</sub> (see <a href="#">Figure 1</a> and <a href="#">Figure 2</a> )	I <sub>S</sub> = 4 mA	1.1 V	17	40	Ω
			1.65 V	7	20	
		I <sub>S</sub> = 8 mA	2.3 V	4	15	
r <sub>on(p)</sub> Peak on resistance	V <sub>I</sub> = V <sub>CC</sub> to GND, V <sub>C</sub> = V <sub>IH</sub> (see <a href="#">Figure 1</a> and <a href="#">Figure 2</a> )	I <sub>S</sub> = 4 mA	1.1 V	131	180	Ω
			1.65 V	32	80	
		I <sub>S</sub> = 8 mA	2.3 V	15	20	
Δr <sub>on</sub> Difference of on-state resistance between switches	V <sub>I</sub> = V <sub>CC</sub> to GND, V <sub>C</sub> = V <sub>IH</sub> (see <a href="#">Figure 1</a> and <a href="#">Figure 2</a> )	I <sub>S</sub> = 4 mA	1.1 V		3	Ω
			1.65 V		1	
		I <sub>S</sub> = 8 mA	2.3 V		1	
I <sub>S(off)</sub> Off-state switch leakage current	V <sub>I</sub> = V <sub>CC</sub> and V <sub>O</sub> = GND, or V <sub>I</sub> = GND and V <sub>O</sub> = V <sub>CC</sub> , V <sub>C</sub> = V <sub>IL</sub> (see <a href="#">Figure 3</a> )		2.7 V		±1	μA
					±0.1 <sup>(2)</sup>	
I <sub>S(on)</sub> On-state switch leakage current	V <sub>I</sub> = V <sub>CC</sub> or GND, V <sub>C</sub> = V <sub>IH</sub> , V <sub>O</sub> = Open (see <a href="#">Figure 4</a> )		2.7 V		±1	μA
					±0.1 <sup>(2)</sup>	
I <sub>I</sub> Control input current	V <sub>I</sub> = V <sub>CC</sub> or GND		0 to 2.7 V		±5	μA
I <sub>CC</sub> Supply current	V <sub>I</sub> = V <sub>CC</sub> or GND, I <sub>O</sub> = 0		0.8 V to 2.7 V		10	μA
C <sub>ic</sub> Control input capacitance			2.5 V		2.5	pF
C <sub>io(off)</sub> Switch input/output capacitance			2.5 V		3	pF
C <sub>io(on)</sub> Switch input/output capacitance			2.5 V		7	pF

(1) t<sub>a</sub> = 25°C

(2) The data was taken at C<sub>L</sub> = 15 pF, R<sub>L</sub> = 2 kΩ (see [Figure 1](#)).

# SN74AUC2G66

## DUAL BILATERAL ANALOG SWITCH

SCES507A–NOVEMBER 2003–REVISED JANUARY 2007

### Switching Characteristics

over recommended operating free-air temperature range,  $C_L = 15 \text{ pF}$  (unless otherwise noted) (see [Figure 5](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 0.8 \text{ V}$	$V_{CC} = 1.2 \text{ V} \pm 0.1 \text{ V}$	$V_{CC} = 1.5 \text{ V} \pm 0.1 \text{ V}$	$V_{CC} = 1.8 \text{ V} \pm 0.15 \text{ V}$	$V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$	UNIT
			TYP	MIN	MAX	MIN	MAX	
$t_{pd}^{(1)}$	A or B	B or A	1	0.6		0.5	0.5	0.4
$t_{en}$	C	A or B	5	0.5	3	0.5	2.1	0.5
$t_{dis}$	C	A or B	5.3	0.5	4	0.5	3	0.5
						0.5	2.6	3.3
						0.5	2.7	ns

(1) The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance when driven by an ideal voltage source (zero output impedance).

### Switching Characteristics

over recommended operating free-air temperature range,  $C_L = 30 \text{ pF}$  (unless otherwise noted) (see [Figure 5](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 1.8 \text{ V} \pm 0.15 \text{ V}$	$V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$	UNIT			
			MIN	TYP	MAX	MIN	MAX	
$t_{pd}^{(1)}$	A or B	B or A		0.7		0.7	0.7	ns
$t_{en}$	C	A or B	0.5	1.6	2.7	0.5	2.3	ns
$t_{dis}$	C	A or B	0.5	2.7	3.4	0.5	2	ns

(1) The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance when driven by an ideal voltage source (zero output impedance).

### Analog Switch Characteristics

$T_A = 25^\circ\text{C}$

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	$V_{CC}$	TYP	UNIT
Frequency response (switch ON)	A or B	B or A	$C_L = 50 \text{ pF}, R_L = 600 \Omega, f_{in} = \text{sine wave}$ (see <a href="#">Figure 6</a> )	0.8 V	101	MHz
				1.1 V	150	
				1.4 V	175	
				1.65 V	250	
				2.3 V	400	
			$C_L = 5 \text{ pF}, R_L = 50 \Omega, f_{in} = \text{sine wave}$ (see <a href="#">Figure 6</a> )	0.8 V	450	
				1.1 V	>500	
				1.4 V	>500	
				1.65 V	>500	
				2.3 V	>500	
Crosstalk (between switches)	A or B	B or A	$C_L = 50 \text{ pF}, R_L = 600 \Omega, f_{in} = 1 \text{ MHz}$ (sine wave) (see <a href="#">Figure 7</a> )	0.8 V	-60	dB
				1.1 V	-60	
				1.4 V	-60	
				1.65 V	-60	
				2.3 V	-60	
			$C_L = 5 \text{ pF}, R_L = 50 \Omega, f_{in} = 1 \text{ MHz}$ (sine wave) (see <a href="#">Figure 7</a> )	0.8 V	-65	
				1.1 V	-65	
				1.4 V	-65	
				1.65 V	-65	
				2.3 V	-65	

### Analog Switch Characteristics (continued)

$T_A = 25^\circ\text{C}$

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	$V_{CC}$	TYP	UNIT
Crosstalk (control input to signal output)	C	A or B	$C_L = 50 \text{ pF}, R_L = 600 \Omega, f_{in} = 1 \text{ MHz}$ (square wave) (see Figure 8)	0.8 V	9	mV
				1.1 V	14	
				1.4 V	15	
				1.65 V	16	
				2.3 V	20	
Feedthrough attenuation (switch OFF)	A or B	B or A	$C_L = 50 \text{ pF}, R_L = 600 \Omega, f_{in} = 1 \text{ MHz}$ (sine wave) (see Figure 9)	0.8 V	-50	dB
				1.1 V	-50	
				1.4 V	-50	
				1.65 V	-50	
				2.3 V	-50	
		B or A	$C_L = 5 \text{ pF}, R_L = 50 \Omega, f_{in} = 1 \text{ MHz}$ (sine wave) (see Figure 9)	0.8 V	-60	
				1.1 V	-60	
				1.4 V	-60	
				1.65 V	-60	
				2.3 V	-60	
Sine-wave distortion	A or B	B or A	$C_L = 50 \text{ pF}, R_L = 10 \text{ k}\Omega, f_{in} = 1 \text{ kHz}$ (sine wave) (see Figure 10)	0.8 V	7	%
				1.1 V	0.256	
				1.4 V	0.04	
				1.65 V	0.03	
				2.3 V	0.01	
	A or B	B or A	$C_L = 50 \text{ pF}, R_L = 10 \text{ k}\Omega, f_{in} = 10 \text{ kHz}$ (sine wave) (see Figure 10)	0.8 V	3.7	
				1.1 V	0.4	
				1.4 V	0.04	
				1.65 V	0.02	
				2.3 V	0.02	

### Operating Characteristics

$T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	$V_{CC} = 0.8 \text{ V}$	$V_{CC} = 1.2 \text{ V}$	$V_{CC} = 1.5 \text{ V}$	$V_{CC} = 1.8 \text{ V}$	$V_{CC} = 2.5 \text{ V}$	UNIT
		TYP	TYP	TYP	TYP	TYP	
$C_{pd}$	Power dissipation capacitance $f = 10 \text{ MHz}$	2.5	2.5	2.5	2.5	2.5	pF

PARAMETER MEASUREMENT INFORMATION

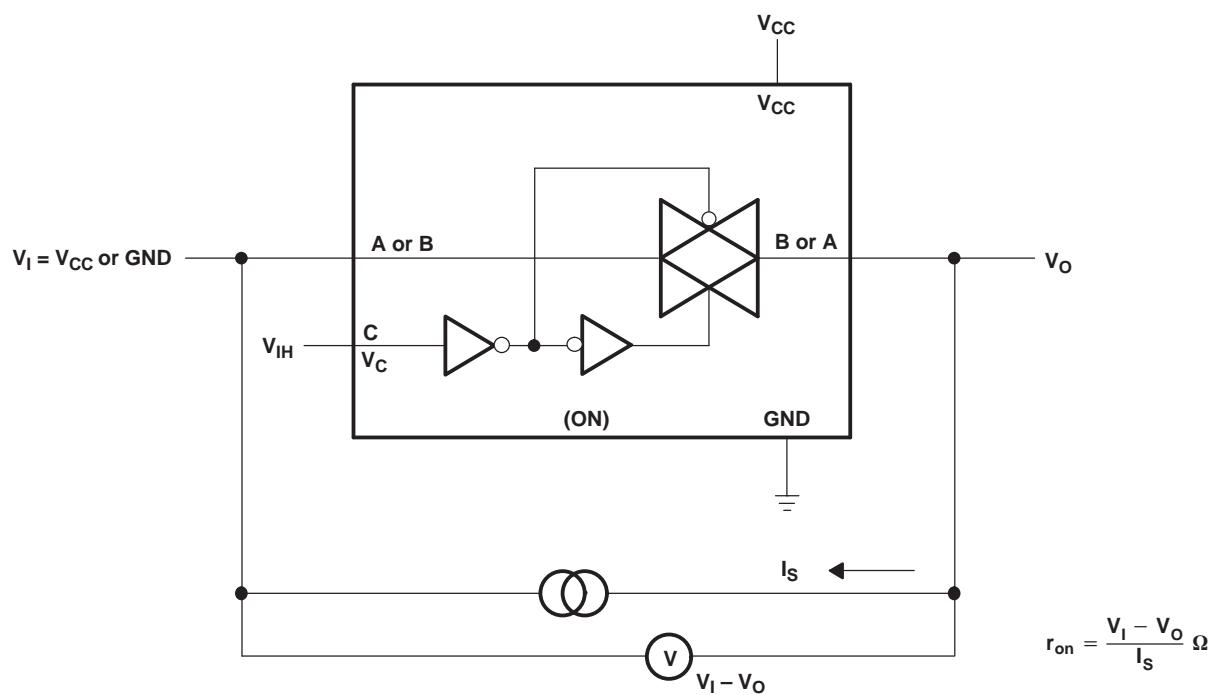


Figure 1. On-State Resistance Test Circuit

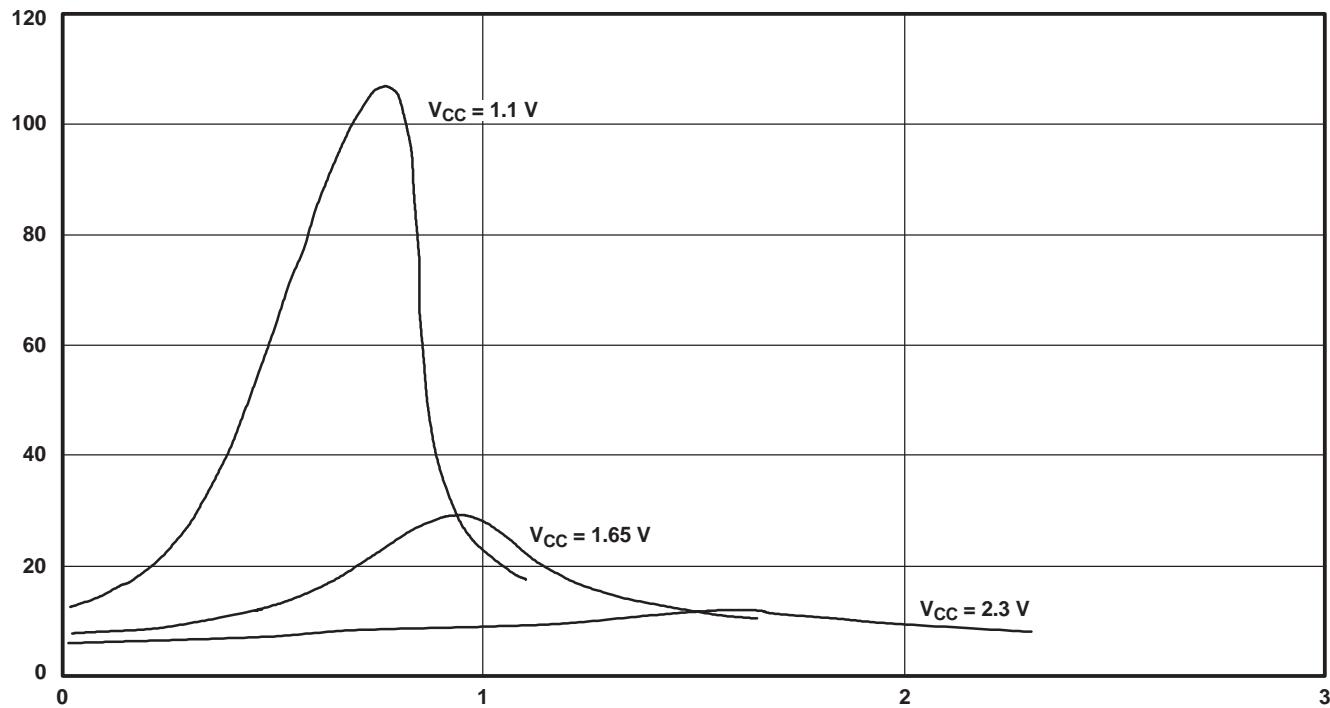


Figure 2. Typical  $r_{on}$  as a Function of Voltage ( $V_I$ ) for  $V_I = 0$  to  $V_{CC}$

PARAMETER MEASUREMENT INFORMATION

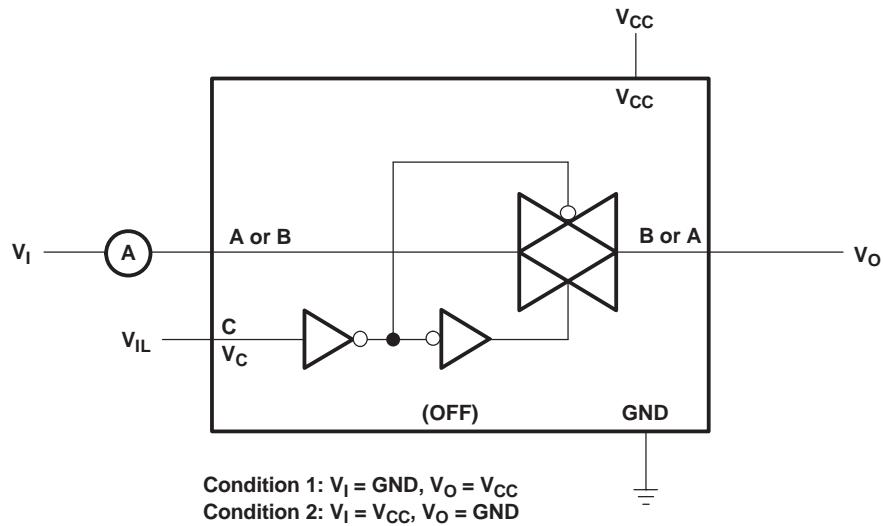


Figure 3. Off-State Switch Leakage-Current Test Circuit

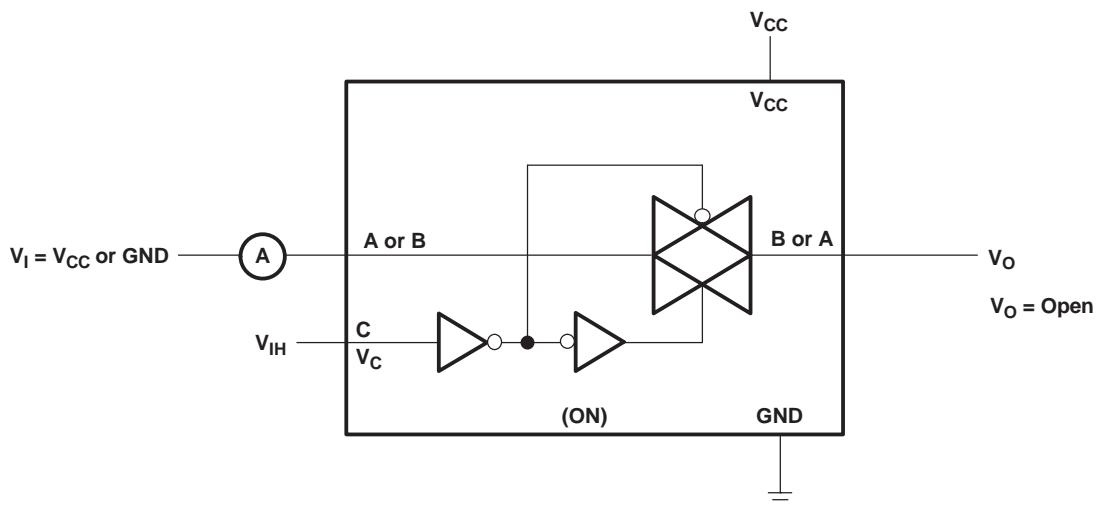
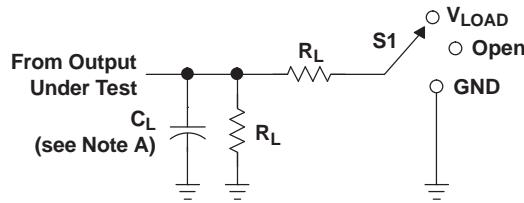


Figure 4. On-State Leakage-Current Test Circuit

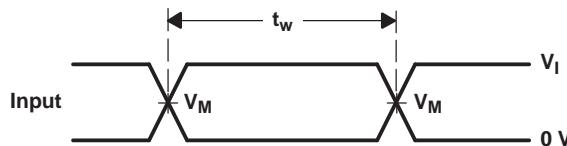
**PARAMETER MEASUREMENT INFORMATION**



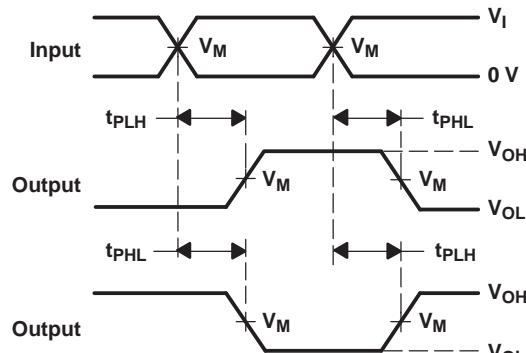
TEST	S1
$t_{PLH}/t_{PHL}$	Open
$t_{PLZ}/t_{PZL}$	$V_{LOAD}$
$t_{PHZ}/t_{PZH}$	GND

**LOAD CIRCUIT**

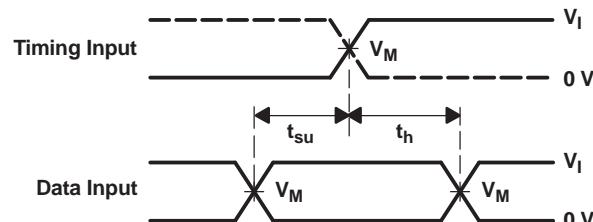
$V_{CC}$	INPUTS		$V_M$	$V_{LOAD}$	$C_L$	$R_L$	$V_\Delta$
	$V_I$	$t_r/t_f$					
0.8 V	$V_{CC}$	$\leq 2$ ns	$V_{CC}/2$	$2 \times V_{CC}$	15 pF	2 k $\Omega$	0.1 V
$1.2 \text{ V} \pm 0.1 \text{ V}$	$V_{CC}$	$\leq 2$ ns	$V_{CC}/2$	$2 \times V_{CC}$	15 pF	2 k $\Omega$	0.1 V
$1.5 \text{ V} \pm 0.1 \text{ V}$	$V_{CC}$	$\leq 2$ ns	$V_{CC}/2$	$2 \times V_{CC}$	15 pF	2 k $\Omega$	0.1 V
$1.8 \text{ V} \pm 0.15 \text{ V}$	$V_{CC}$	$\leq 2$ ns	$V_{CC}/2$	$2 \times V_{CC}$	15 pF	2 k $\Omega$	0.15 V
$2.5 \text{ V} \pm 0.2 \text{ V}$	$V_{CC}$	$\leq 2$ ns	$V_{CC}/2$	$2 \times V_{CC}$	15 pF	2 k $\Omega$	0.15 V
$1.8 \text{ V} \pm 0.15 \text{ V}$	$V_{CC}$	$\leq 2$ ns	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	1 k $\Omega$	0.15 V
$2.5 \text{ V} \pm 0.2 \text{ V}$	$V_{CC}$	$\leq 2$ ns	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	500 $\Omega$	0.15 V



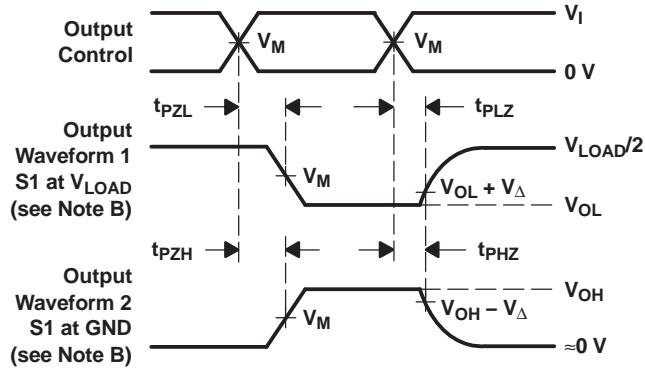
**VOLTAGE WAVEFORMS  
PULSE DURATION**



**VOLTAGE WAVEFORMS  
PROPAGATION DELAY TIMES  
INVERTING AND NONINVERTING OUTPUTS**



**VOLTAGE WAVEFORMS  
SETUP AND HOLD TIMES**



**VOLTAGE WAVEFORMS  
ENABLE AND DISABLE TIMES  
LOW- AND HIGH-LEVEL ENABLING**

NOTES: A.  $C_L$  includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq 10$  MHz,  $Z_O = 50 \Omega$ , slew rate  $\geq 1$  V/ns.
- D. The outputs are measured one at a time, with one transition per measurement.
- E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
- F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
- G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .
- H. All parameters and waveforms are not applicable to all devices.

**Figure 5. Load Circuit and Voltage Waveforms**

PARAMETER MEASUREMENT INFORMATION

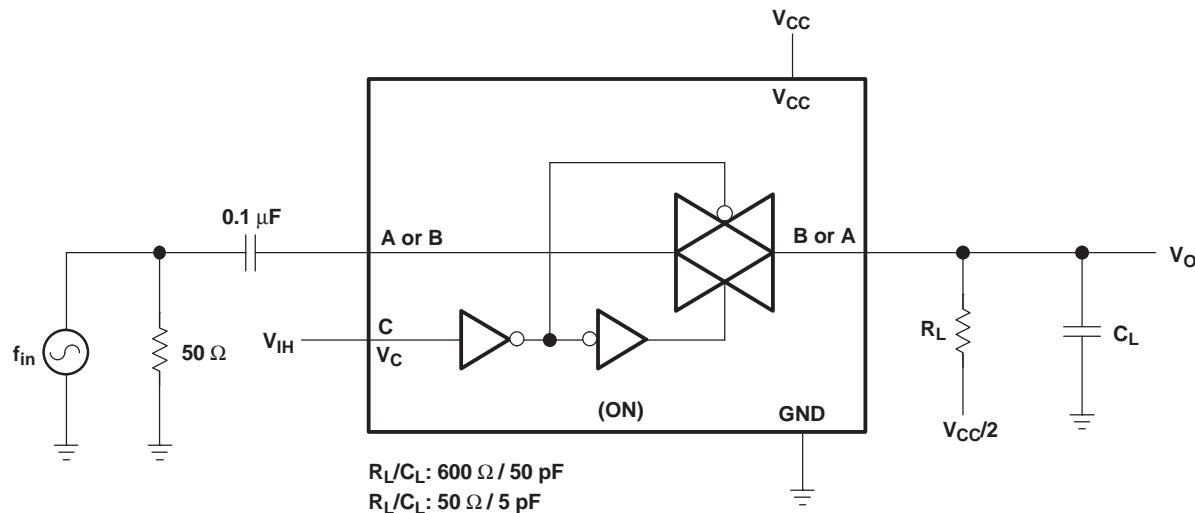


Figure 6. Frequency Response (Switch ON)

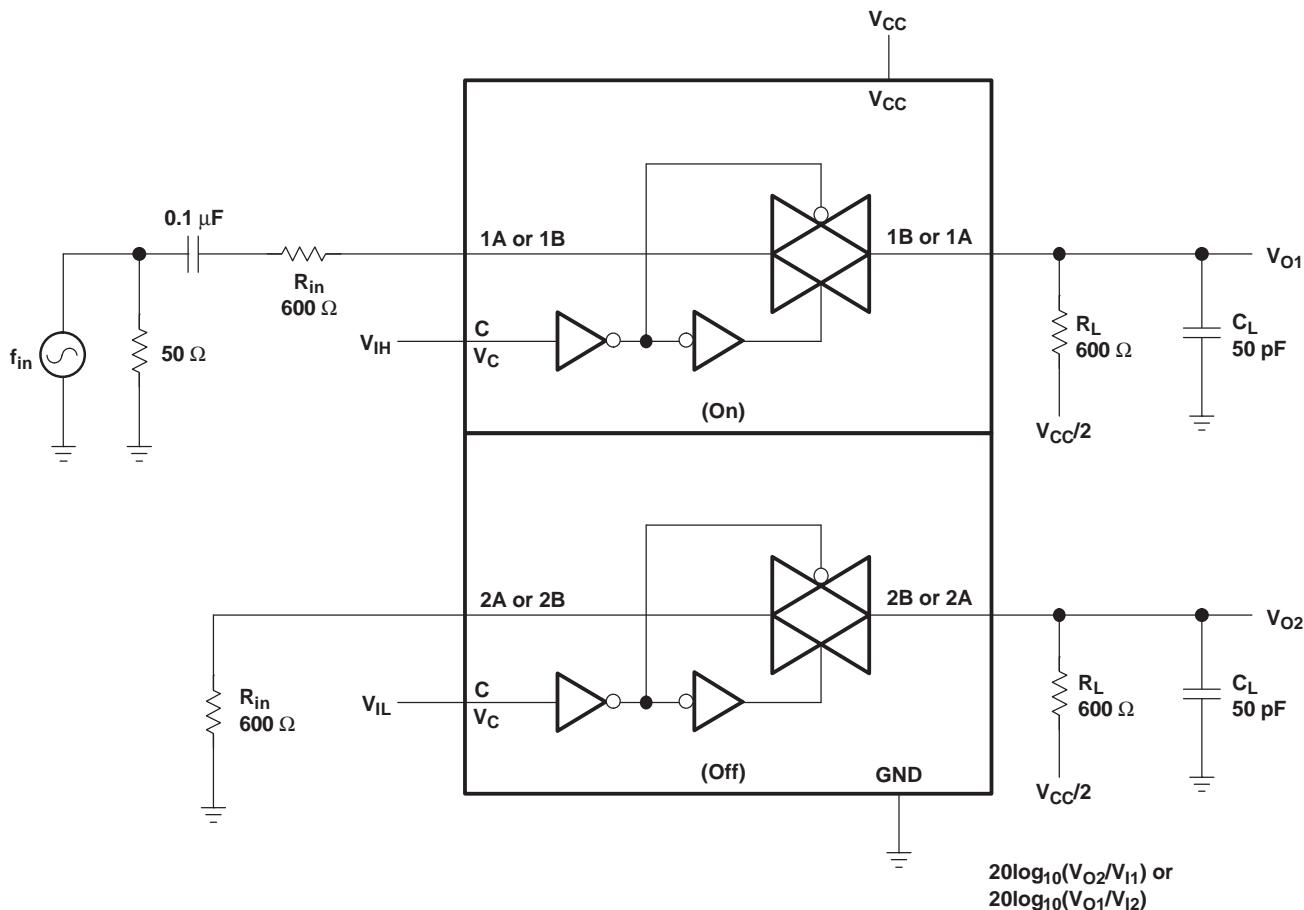
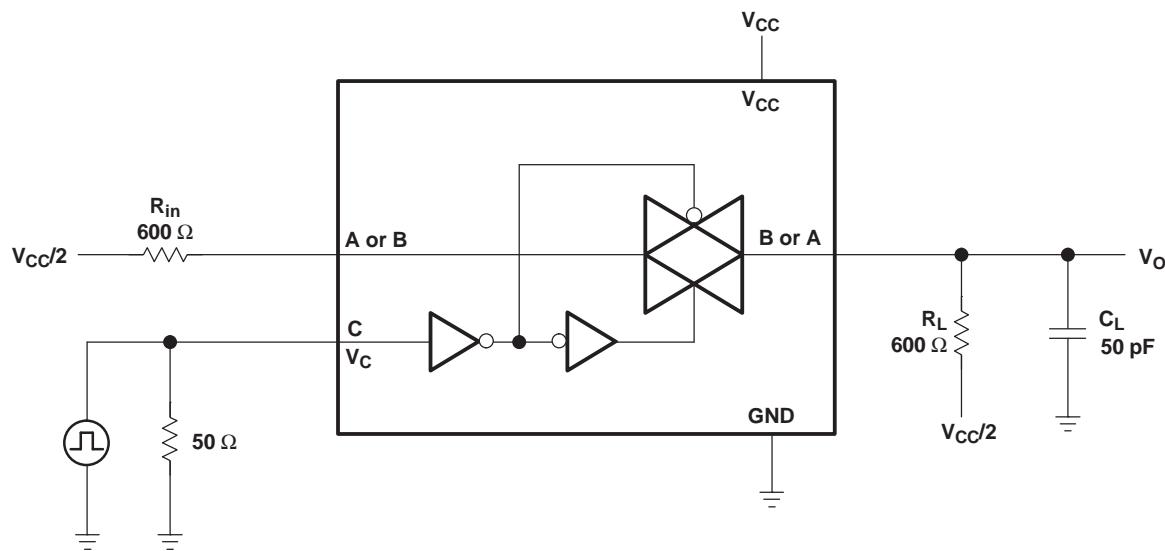
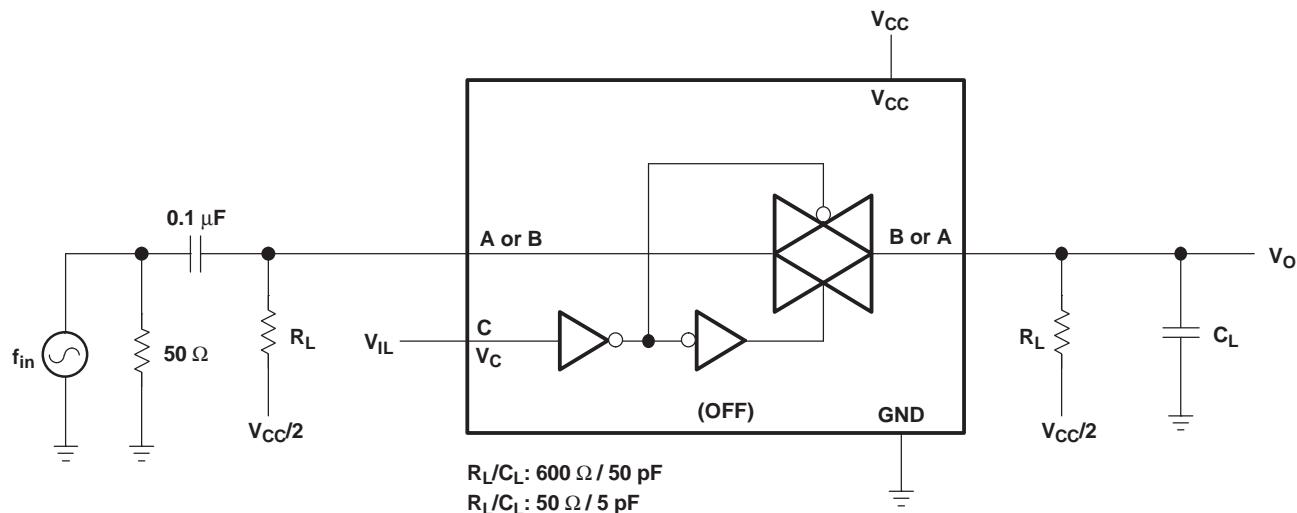


Figure 7. Crosstalk (Between Switches)

**PARAMETER MEASUREMENT INFORMATION**



**Figure 8. Crosstalk (Control Input – Switch Output)**



**Figure 9. Feedthrough, Switch Off**

PARAMETER MEASUREMENT INFORMATION

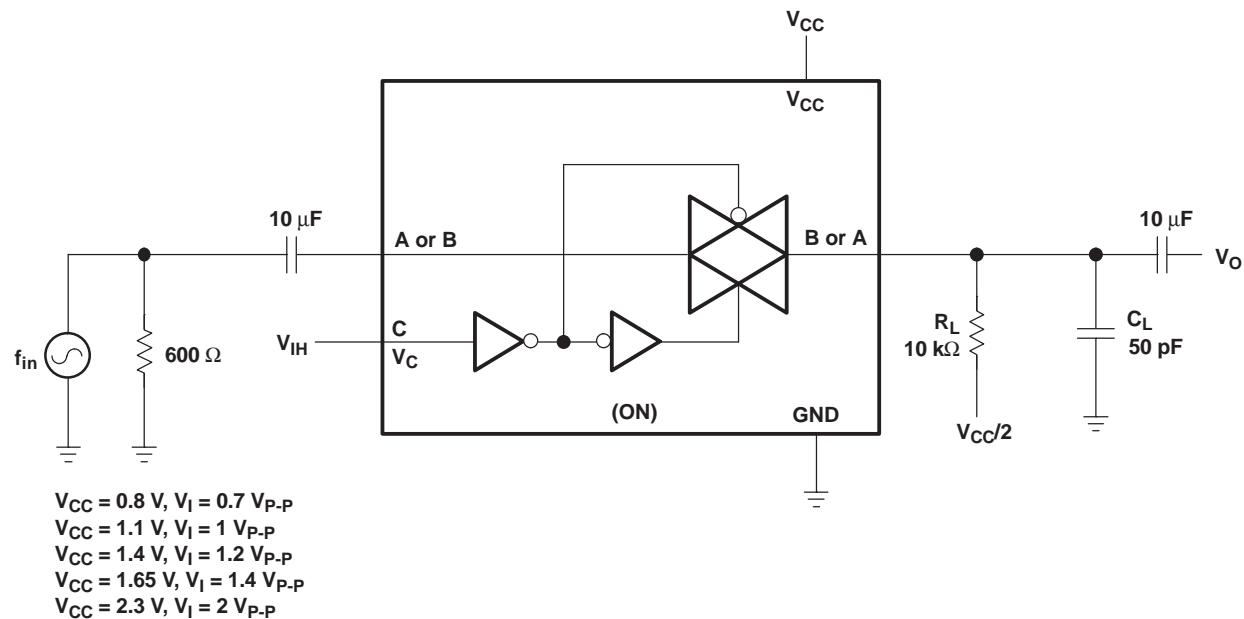


Figure 10. Sine-Wave Distortion

## PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
SN74AUC2G66DCTR	ACTIVE	SM8	DCT	8	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	U66Z	<b>Samples</b>
SN74AUC2G66DCTRE4	ACTIVE	SM8	DCT	8	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	U66Z	<b>Samples</b>
SN74AUC2G66DCTRG4	ACTIVE	SM8	DCT	8	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	U66Z	<b>Samples</b>
SN74AUC2G66DCUR	ACTIVE	US8	DCU	8	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	(66 ~ U66R) (UR ~ UZ)	<b>Samples</b>
SN74AUC2G66DCURE4	ACTIVE	US8	DCU	8	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	U66R	<b>Samples</b>
SN74AUC2G66DCURG4	ACTIVE	US8	DCU	8	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	U66R	<b>Samples</b>
SN74AUC2G66YZPR	ACTIVE	DSBGA	YZP	8	3000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	-40 to 85	U67	<b>Samples</b>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.



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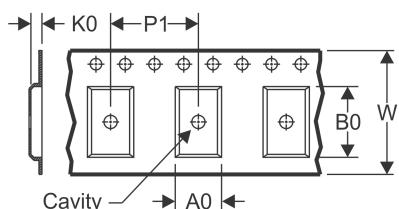
## PACKAGE OPTION ADDENDUM

11-Apr-2013

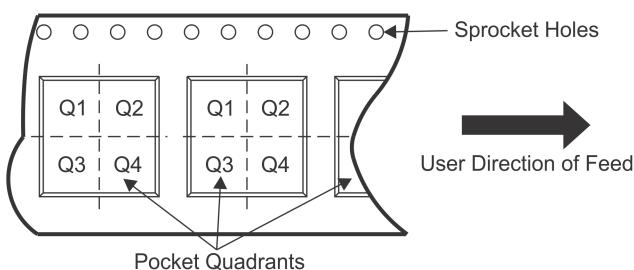
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**TAPE AND REEL INFORMATION**
**REEL DIMENSIONS**

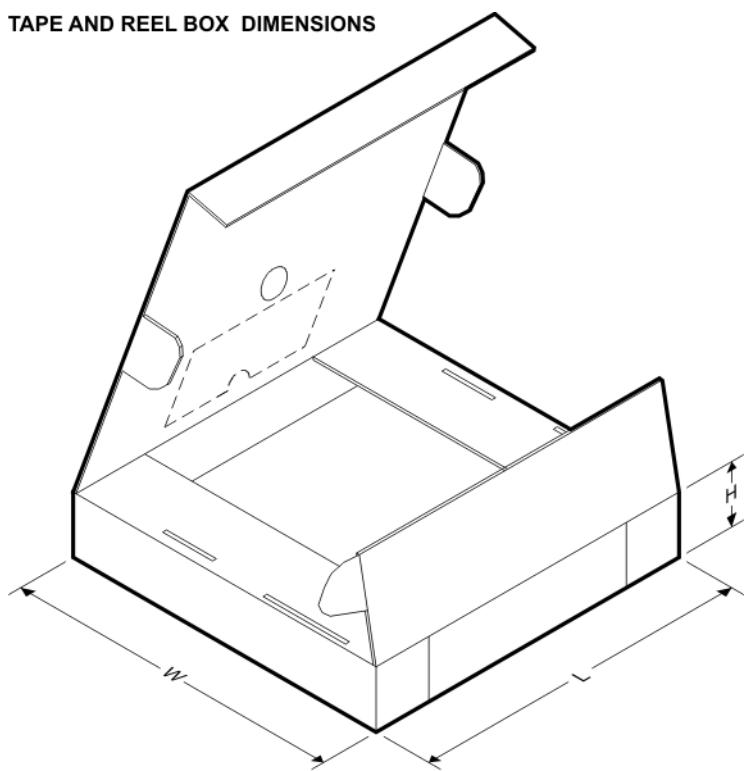
**TAPE DIMENSIONS**


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AUC2G66DCUR	US8	DCU	8	3000	180.0	8.4	2.25	3.35	1.05	4.0	8.0	Q3
SN74AUC2G66DCURG4	US8	DCU	8	3000	180.0	8.4	2.25	3.35	1.05	4.0	8.0	Q3
SN74AUC2G66YZPR	DSBGA	YZP	8	3000	180.0	8.4	1.02	2.02	0.63	4.0	8.0	Q1

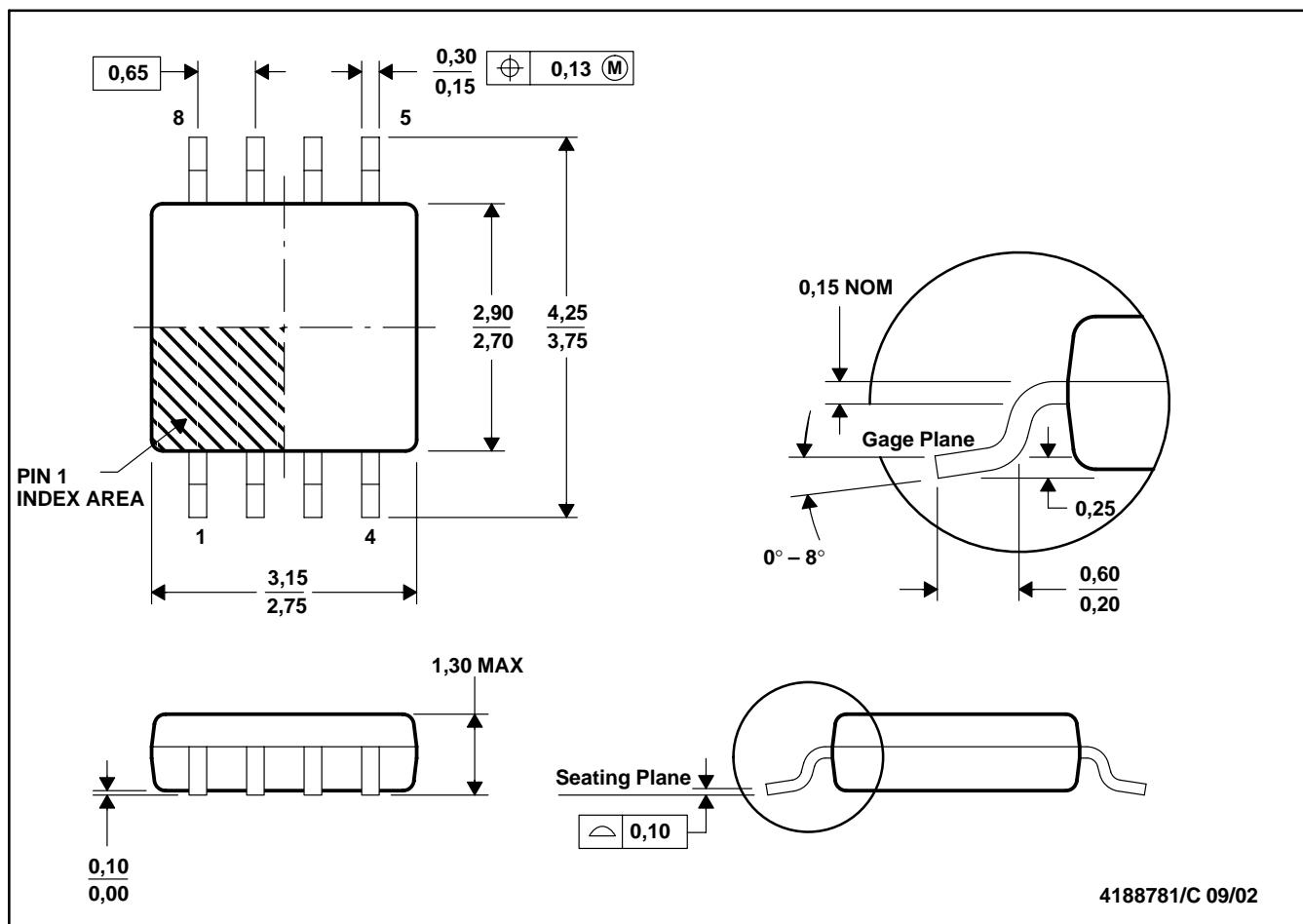
**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AUC2G66DCUR	US8	DCU	8	3000	202.0	201.0	28.0
SN74AUC2G66DCURG4	US8	DCU	8	3000	202.0	201.0	28.0
SN74AUC2G66YZPR	DSBGA	YZP	8	3000	220.0	220.0	34.0

## DCT (R-PDSO-G8)

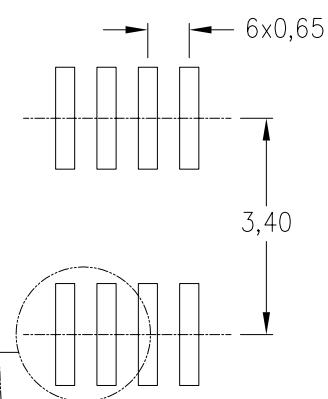
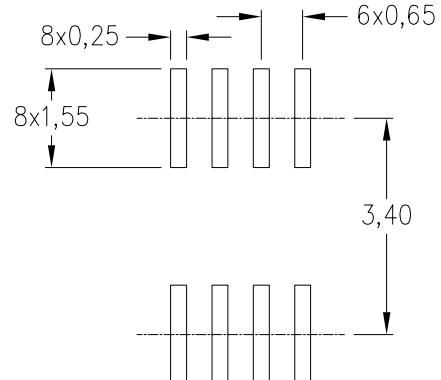
## PLASTIC SMALL-OUTLINE PACKAGE



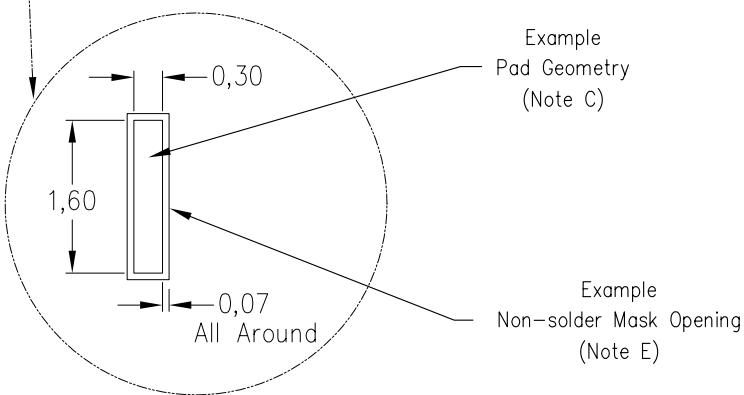
NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion  
 D. Falls within JEDEC MO-187 variation DA.

DCT (R-PDSO-G8)

PLASTIC SMALL OUTLINE

Example Board Layout  
(Note C,E)Example Stencil Design  
(Note D)

Non Solder Mask Defined Pad

Example  
Pad Geometry  
(Note C)Example  
Non-solder Mask Opening  
(Note E)

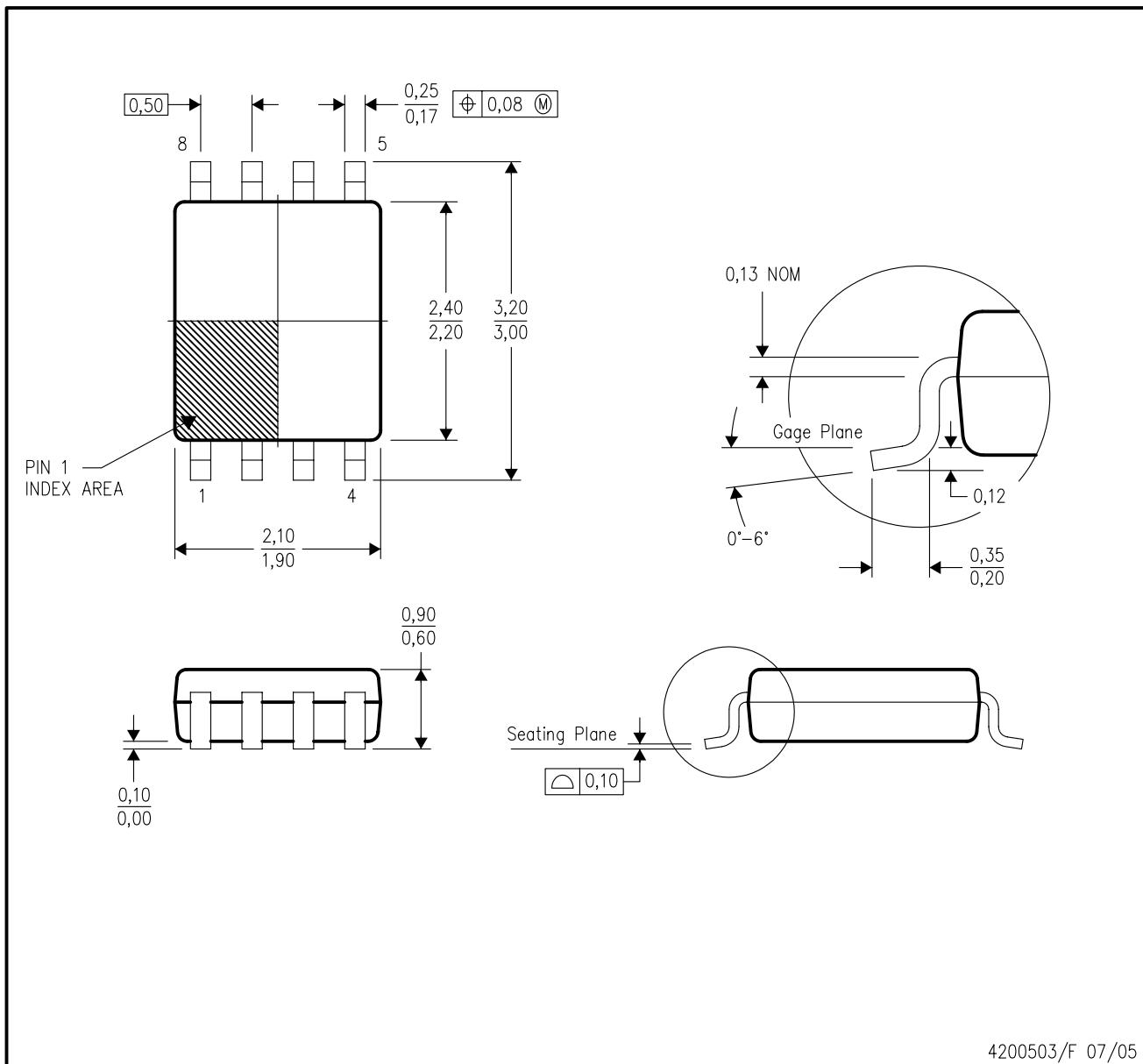
4212201/A 10/11

NOTES:

- All linear dimensions are in millimeters.
- This drawing is subject to change without notice.
- Publication IPC-7351 is recommended for alternate designs.
- Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525.
- Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

## DCU (R-PDSO-G8)

## PLASTIC SMALL-OUTLINE PACKAGE (DIE DOWN)



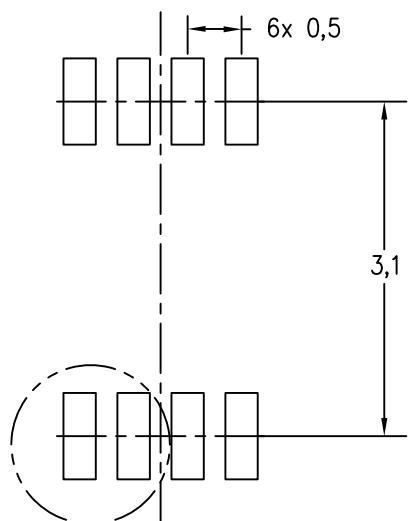
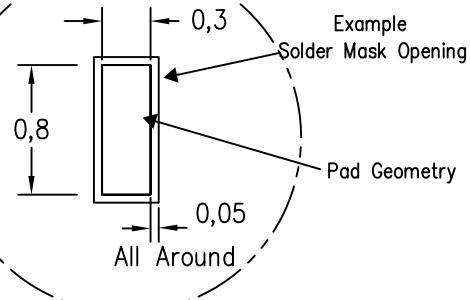
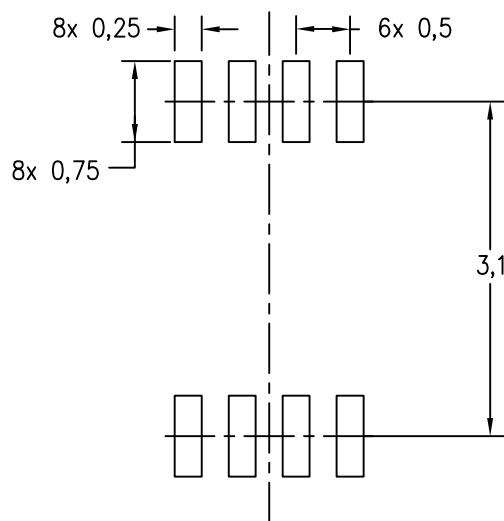
4200503/F 07/05

NOTES:

- All linear dimensions are in millimeters.
- This drawing is subject to change without notice.
- Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
- Falls within JEDEC MO-187 variation CA.

DCU (S-PDSO-G8)

PLASTIC SMALL OUTLINE PACKAGE (DIE DOWN)

Example Board Layout  
(Note C,E)Example Stencil Design  
(Note D)

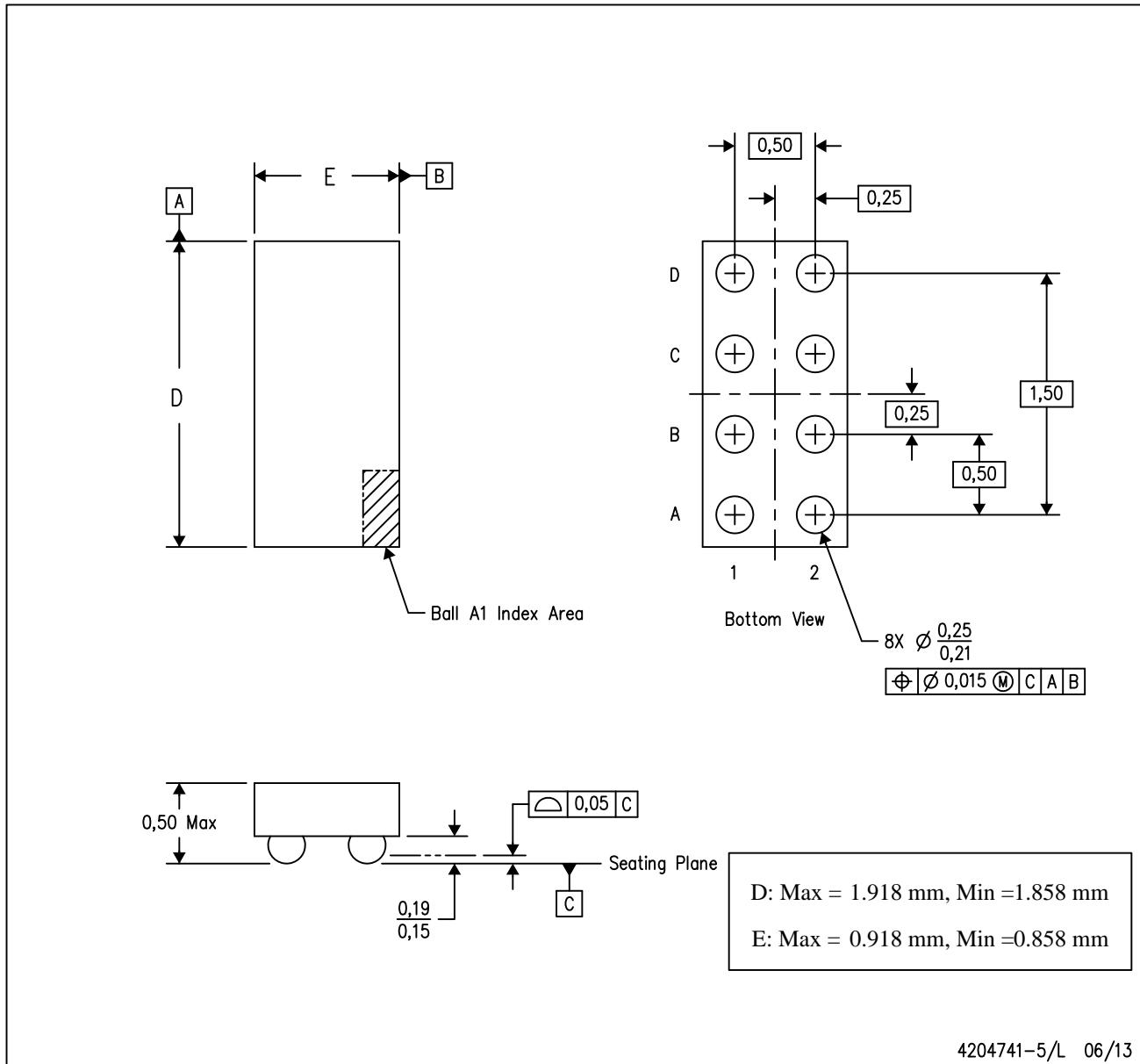
4210064/C 04/12

NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

YZP (R-XBGA-N8)

DIE-SIZE BALL GRID ARRAY



NOTES:

- All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
- This drawing is subject to change without notice.
- NanoFree™ package configuration.

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